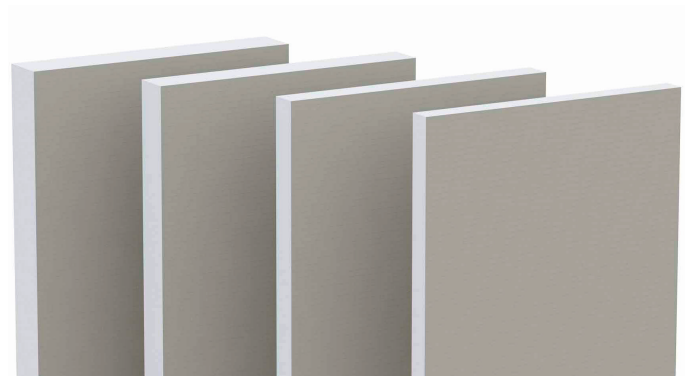


# Technical data sheet

## XPS hard foam board

- suitable for indoor wall and floor application
- heat insulating
- light
- pressure resistant
- bending resistant
- stable
- quick and easy to apply
- variable usable



### General product description

The XPS hard foam board consists of a core of XPS foam reinforced on both sides with a glass fiber scrim and coated with a mortar.

### Applications

The XPS hard foam board is versatile due to its special properties:

- suitable for direct laying of tiles and slabs using the thin-bed method
- suitable for direct application for filler and plaster
- no primer before applying the tile adhesive needed
- can be used for indoor insulation
- is ideally suited for the wet room in combination with sealing system
- the XPS hard foam board is approved for indoor use in rooms with normal temperature

The XPS hard foam board can be processed with all commercially available tools, such as: cutter knife, hand saw, jigsaw, hand circular saw, table circular saw.

### Surface requirements, laying

The XPS hard foam board must be installed on load-bearing substrates.

XPS hard foam boards thinner than 12.5 mm:

- stud frame application **not** approved
- glue onto a load-bearing substrate over the entire surface (without cavities)

XPS hard foam boards with thickness  $\geq 12.5$  mm:

- glue or screw to load-bearing stud frame with a stud frame spacing of max. 300 mm (8 screws per XPS hard foam board)
- alternatively, glue over the entire surface

XPS hard foam boards with thickness  $\geq 20$  mm:

- Glue or screw to load-bearing stud frame with a stud frame spacing of max. 600 mm (8 screws per XPS hard foam board)
- alternatively, glue over the entire surface

# Technical data sheet

## Technical properties XPS hard foam board

Tensile strength	≥0.2 N/mm <sup>2</sup>
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## Technical properties of raw foam

Thermal conductivity	Min. 0.036 W/mK
Compressive resistance or compressive strength at 10% compression	Min. 0.25 N/mm <sup>2</sup>
Density	30 kg/m <sup>3</sup> (+1/-1)
Tensile strength perpendicular to the panel plane	0.4 N/mm <sup>2</sup>
Temperature limits	up to max. 70°
Resistance to water vapour diffusion (μ) EN 12086	80

## Form

Delivery thickness	4 – 50 mm
Delivery format	1300/2600 x 600 mm